

TEST RELIABILITY AND SECURITY CHALLENGES IN VLSI SYSTEMS

CALL FOR PAPERS

The IEEE VLSI Test Symposium (VTS) explores emerging trends and novel concepts in test, calibration, validation, yield, reliability and security of microelectronic circuits and systems. The VTS Program Committee invites original, unpublished paper submissions for VTS 2023. Proposals for the innovative practices and special sessions tracks are also invited.

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Major topics include but are not limited to:

Analog, Mixed-Signal, RF Test	Embedded System & Board Test	On-Line Test & Error Correction
ATPG & Compression	Test	Power & Thermal Issues in Test
Silicon Debug	Embedded Test Methods	System-on-Chip (SOC) Test
Automotive Test & Safety	Emerging Technologies Test and Reliability	Test & Reliability of Biomedical Devices
Built-In Self-Test (BIST)	Fault Modeling and Simulation	Test & Reliability of High-Speed I/O
Defect & Current Based Test	Low-Power IC Test	Test & Reliability of Machine Learning Systems
Defect & Fault Tolerance	Machine Learning in Test, Yield and Reliability	Test Quality & Reliability
Delay & Performance Test	Microsystems/MEMS/Sensors Test	Test Standards & Economics
Design for Testability, Yield or Reliability	Memory Test and Repair	Test Resource Partitioning
Pre-silicon Design Verification & Validation	2.5D, 3D & SiP Test	Transient & Soft Errors
Post-silicon Validation	Yield Optimization	FPGA Test
Hardware Security		

New hot topics:

This year VTS puts particular emphasis on enlarging its scope soliciting submissions on **silent data corruption as well as testing, reliability and security aspects of AI, machine learning systems, neuromorphic devices, and quantum computing.**

Key Dates:

Paper registration:
October 21, 2022

Paper PDF upload:
October 28, 2022

Questions to authors:
December 2, 2022

Submission of rebuttal:
December 9, 2022

Notification of acceptance:
December 23, 2022

Camera-ready upload:
February 03, 2023

Submissions:

Scientific Papers: complete manuscripts, up to 6 pages in standard IEEE two-column format (references do not count towards the page limit).

Special Session and Innovative Practices Proposals: Proposals may include presentations on hot topics, panels, embedded tutorials. Every proposal must include a 150-to-200 word abstract, the name of the organizers and a list of at least three speakers with a tentative presentation title. The VTS review process is DOUBLE BLIND with REBUTTAL.

Submit your papers at:

<https://welcome.molesystems.com/ttcc/VTS/2023>

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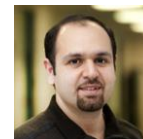
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